

■ TUESDAY, APRIL 14th

Pre-conference Networking

- 9:30 Official Exhibition Opening
- 11:00 Exhibition Visits / Refreshments / Networking

Conference Session 1: Trends in Automotive Electronics and Resulting Demands on Material Diagnostics and Quality Assurance

- 11:00 Welcome
- 11:10 Engineering the Robustness of Tomorrow's Automotive Electronics Solutions
Uwe Girgsdies, Wolfgang Fröhlich | AUDI AG | DE
- 11:50 Electric Traction in Automotive Vehicles: Current Developments and Challenges on Material Diagnostics
Urs Boehme, Alexander Nisch, Wolfgang Wondrak | Daimler AG | DE
- 12:20 Memory Components in Future Automotive Electronics - Chances, Perspectives and Challenges
Ivan Ivanov | Micron Semiconductor GmbH | DE
- 12:50 MEMS Reliability – Current Status and Challenges
Mervi Paulasto-Kröckel | Aalto University | FI
Heikki Kuisma | Murata Electronics Oy | FI
- 13:20 Lunch Break / Industrial Exhibition / Networking

Conference Session 2: Current Challenges in Automotive Electronics Failure Diagnostics

- 14:50 Failure Analysis and Reliability Challenges for Automotive Electronics
Jörg Krinke | Robert Bosch GmbH | DE
- 15:20 Zero Defect in Automotive Failure Analysis
Oliver Senftleben | AUDI AG | DE
- 15:45 Failure Analysis Challenges - A View from Medium-Sized Manufacturer
Jürgen Schulz, Matthias Gratz, Alexander Seibt, Gwenaëlle Page, Bernadette Vrijns | Melexis GmbH | DE, BE
- 16:10 Challenges on Upstream Verification and Root Cause Analysis in Modern Day Automotive Applications
Michael Otte, Michael Kilian, Christoph Thiele | Texas Instruments Deutschland GmbH | DE

- 16:35 Failure Analysis for Bare Dies: Where the Cooperation with Customers May Be the Biggest Challenge for a Successful Analysis
Claudia Keller, Wolfgang Buerkle | Infineon AG | DE
- 17:00 Drinks Reception / Industrial Exhibition / Networking
- 20:00 Networking Dinner

■ WEDNESDAY, APRIL 15th

Conference Session 3: Failure Analysis Solutions and Results on Semiconductor, Package and Sub-system Level

- 8:15 Failure Analysis Study Using AFM Nanoprobing and Scanning Capacitance Microscopy
Abdellatif Firti | NXP | NL
- 8:40 CAF in Printed Circuit Boards: An Investigation of the Interface Between Glass Fiber and Epoxy
Bhanu Sood | Center for Advanced Lifecycle Engineering CALCE | USA
- 9:05 From Failure Analysis to Failure Prevention
Edwin Vonk | Sensata Technologies Holland B.V. | NL
- 9:30 Failure Analysis Case Studies on Automotive Electronics Components
Christopher Schierholz | Continental AG | DE
- 9:55 LED Malfunctions Caused by Inadequate Circuitry and / or Hermetically Sealing
Peter Jacob | EMPA | CH
- 10:20 Coffee Break / Industrial Exhibition / Networking
- 10:45 Cu-Wires Bonded Products AEC-Q100 Qualification: Results, Challenges and Open Discussable Items
Mykola Blyznyuk, Jian Chen, Nikolay Furman | Melexis | UKR, BE
- 11:15 Prognostic Approaches for Wirebond Failure Prediction in Power Semiconductors
Przemyslaw Jakub Gromala | Robert Bosch GmbH | DE
- 11:40 Advanced Chip Level Defect Localization by Nanoprobing and EBAC Techniques
Jörg Jatzkowski, Frank Altmann | Fraunhofer CAM | DE

- 12:05 Neutron Effects on Non-volatile Memory
Angelo Visconti | Micron Semiconductor Italia S.r.l. | IT
- 12:30 Packages in Harsh Environment: The Need for Close Cooperation with the Customer Demonstrated by a Case Study
Jürgen Walter | Infineon AG | DE
- 12:55 Lunch / Industrial Exhibition / Networking

Conference Session 4: New Methods for Material Characterization of Electronics Materials

- 14:00 Improvement of IDDQ-analysis Through Multiple Emission Microscopy Imaging and Analysis
Gerhard Borgmann, Christian Hollerith | Infineon AG | DE
- 14:25 Multi-photon OBIC Applications
Yoshitaka Iwaki | Hamamatsu Photonics Deutschland GmbH | DE
- 14:50 Lock-in Thermography, an Effective Non-destructive Failure Isolation Method for Automotive Electronics
Antoine Reverdy | Sector Technologies SAS | FR
- 15:15 Coffee Break / Industrial Exhibition / Networking
- 15:45 Scanning Acoustic Microscopy: Novel Approaches and Signal Analysis
Sebastian Brand | Fraunhofer CAM | DE
Peter Czurratis | PVA TePla Analytical Systems GmbH | DE
- 16:10 Magnetic Imaging on Resistive, Capacitive and Inductive Devices; from Theory to Piezoelectric Actuators Failure Localization Application
Philippe Perdu, Nicolas Courjeault and Fulvio Infante | CNES / Intraspec Technologies | FR
- 16:35 A New Generation of High Precision Testing Machines, Used for VHCF Investigations and Experimental Characterization of Connectors in Control Devices
Michael Matthias | ISYS Adaptive Solutions GmbH | DE
- 17:00 Lab Tours and Tool Demos
- 18:00 End of Workshop